

QUESTTECH

Silicon, Silicon Carbide & Piezo Ceramics

Applications

General

- Active Devices NOT Mechanically or Electrically Damaged by processing
- Any shape required--shape complexity is not a limitation
- No hard tooling or non-recurring engineering charge
- No tooling impact for design changes
- Fast delivery of any custom shape or size
- Economical small lot quantities

Types

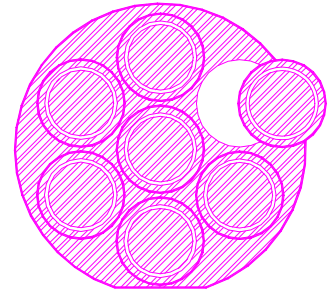
- Optoelectronic Detectors
- Die Placement Templates
- Shadow Masks

Uses

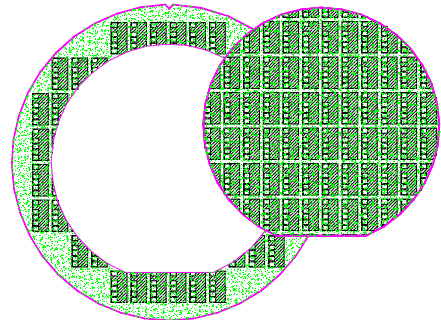
- Down Sizing of Silicon Wafers
- Excising non-rectangular devices
- Reactive Ion Etcher Gas Metering Electrodes

Materials

- Silicon Wafers
- Any Dopant or Crystal Orientation
- Silicon Carbide
- Piezo Ceramics



Typical Detector Application



Typical Down sizing Application

Design Guidelines

Property	Nominal	Units
Smallest Feature	.001	Inches
Minimum Radius	.0005	Inches
Feature Tolerances as cut	+/- .002*	Inches
Thickness Range	.001 to .070	Inches
Front to Back Taper	10%	Of Thickness
Minimum Feature to Feature Proximity	.015	Inches
Minimum Edge Side Wall	1X	Material Thickness
Minimum Kerf Width	.001	Inches
Maximum Resolution	.0002	Inches
Maximum Working Size	6.0 x 6.0**	Inches
Chemical Milling & Cleaning	Available	n/a
Edge Beveling	Available	n/a

* As measured at either Front or Back Side **Up to 12.0 x 12.0 inches depending on specific requirements

Questech Services Corporation
2201 Executive Drive
Garland, Texas 75041 USA

800-736-1664
972-278-8006
Fax: 972-278-8036

e-mail: sales@questlaser.com
Website: www.questlaser.com